

SOT830-1

plastic thermal enhanced thin shrink small outline package/
transparent; no leads; 16 terminals; resin based; body 5.4 x
3.9 x 1.2 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSON16TR
Package type industry code	HTSSON16TR
Package style descriptive code	HTSSON (thermal enhanced thin shrink small outline; no leads)
Package style suffix code	TR (transparent; resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.8	-	3.9	4	mm
E	package width	5.3	-	5.4	5.5	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	[tbd]	-	1.2	[tbd]	mm
n ₂	actual quantity of termination	-	-	16	-	

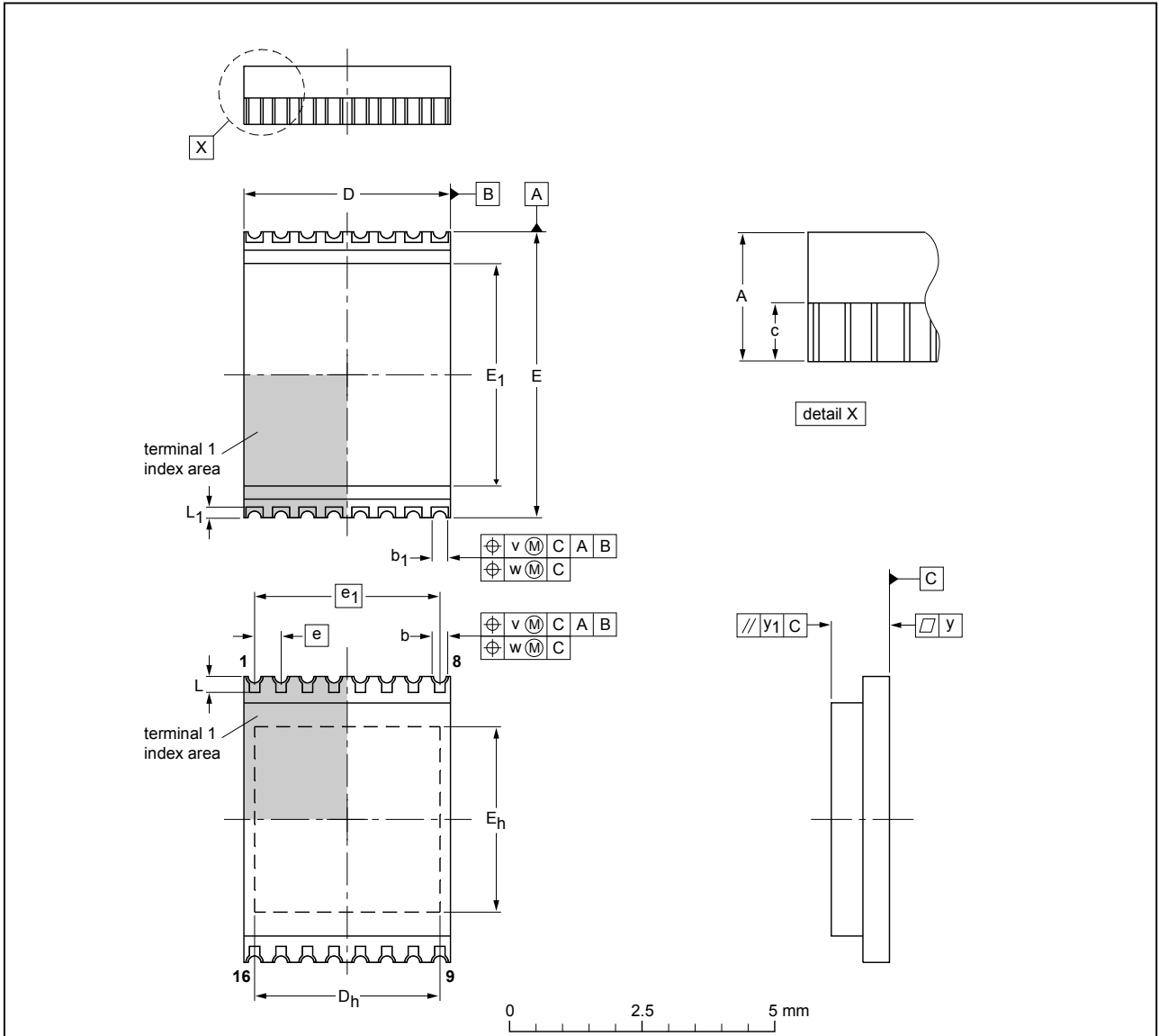


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2. Package outline

HTSSON16TR: plastic thermal enhanced thin shrink small outline package; no leads; 16 terminals; transparent; resin based; body 5.4 x 3.9 x 1.2 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	b	b ₁	c	D	D _h	E	E ₁	E _h	e	e ₁	L	L ₁	v	w	y	y ₁
mm	1.2	0.40 0.25	0.40 0.25	0.7 0.3	4.0 3.8	3.7 3.5	5.5 5.3	4.3 4.1	3.6 3.4	0.5	3.5	0.3	0.2	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT830-1	---	---	---		04-01-07 07-11-14

Fig. 1. Package outline HTSSON16TR (SOT830-1)

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3. Legal information

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